



## Call for Papers

COMCAS 2017 continues the tradition of providing an international, multidisciplinary forum for the exchange of ideas, research results, and industry experience in the areas of microwave/RF/mm-wave engineering, communications, antennas, solid state circuits, electronic devices, engineering in medicine, radar, sonar and electronic systems.

The technical program includes invited talks by international experts and contributed papers and will be complemented by a large industrial exhibition.

### Important Deadlines

**Summary Submission:**  
**April 20, 2017**

**Acceptance Notification:**  
**July 3, 2017**

**Full Paper Submission:**  
**September 4, 2017**

For more information visit:

[www.comcas.org](http://www.comcas.org)

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### Papers are solicited in a wide range of topics:

#### Communications and Sensors

Long Range Low Power Networks  
5G Mobile Communication  
Cognitive Radio & Spectral Sharing  
Software-Defined Radio & Multiple Access  
Micro/Pico/Femtocell Devices and Systems  
MIMO Antenna Systems for Communications  
Modulation & Signal Processing Technologies  
Spatial Coding  
First Responder/Military Communications  
Optical/Wireless Convergence and Integration  
Radio over Fiber  
Sensor Networks and Technologies  
On-Body and Short Range Communications

#### Antennas, Propagation, and Scattering

Smart Antennas, Beamforming and MIMO  
Wave Propagation and Channel Modeling  
Wave Scattering and RCS  
NanoEM, Plasmonics, and Applications  
Metamaterials, FSS and EBG  
EM Field Theory and Numerical Techniques  
EM Interference & Compatibility, SI  
Spectrum Management and Monitoring  
ELF, RF,  $\mu$ Wave, mmW and THz Measurements

#### Signal Processing (SP) and Imaging

Microwave Imaging and Tomography  
Acoustic/Sonar Imaging and Techniques  
Biomedical Image Processing  
Radar SP and Imaging, SAR, ATR  
MIMO SP for Radar  
Ground and Foliage Penetration Systems  
Signal Acquisition and Sensor Management  
DF, Emitter Location, Elint, Array Processing  
Target Detection, Identification and Tracking  
Data Fusion  
Time Domain and UWB SP

#### RF/MW Devices and Circuits, RFICs

Solid-State Devices, RFICs  
 $\mu$ Wave, mmW and Sub-mmW Circuits/Technologies  
Nano and THz Devices/Technologies  
Microwave Photonics  
Passive Components and Circuits  
Filters and Multiplexers  
Ferroelectrics, RF MEMS, MOEMS, and NEMS  
Active Devices and Circuits  
RF Power Amplifiers and Devices  
Tunable and Reconfigurable Circuits/Systems  
Analog/Digital/Mixed RF Circuits  
Circuit Theory, Modeling and Applications  
Interconnects, Packaging and MCM  
CAD Techniques for Devices and Circuits  
Emerging Technologies  
Thermal Management for Devices  
Internet of Things

#### Microwave Systems, Radar, Acoustics

Aeronautical and Space Applications  
RFID Devices/Systems/Applications  
Automotive/Transportation Radar & Communications  
Environmentally Sensitive ("Green") Design  
Biomedical Systems and Applications  
UWB and Multispectral Technologies & Systems  
Emerging System Architectures  
Modelling Techniques for RF Systems  
Radar Techniques, Systems and Applications  
Sonar Systems and Applications  
Wireless Power Transfer & Energy Harvesting  
Terahertz Systems

#### General and Other Topics

Regular verbal presentations will be 20 min. in length; there will also be Poster sessions. All submitted papers will be peer reviewed. Accepted papers will be published in the COMCAS 2017 Proceedings, which will be submitted for inclusion to IEEE Xplore® after the conference. For author's instructions and further information, see [www.comcas.org](http://www.comcas.org).